

NC7WZ04 TinyLogic[®] UHS Dual Inverter

Features

- Ultra-High Speed: t_{PD} 2.3ns (Typical) into 50pF at 5V V_{CC}
- High Output Drive: ±24mA at 3V V_{CC}
- Broad V_{CC} Operating Range: 1.65V to 5.5V
- Matches Performance of LCX when Operated at 3.3V V_{CC}
- Pow er Dow n High Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5V to 3V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages
- Space-Saving SC70 6-Lead Package

Description

The NC7WZ04 is a dual inverter from ON Semiconductor's Ultra-High Speed (UHS) series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive while maintaining low static power dissipation over a broad $V_{\rm CC}$ operating range. The device is specified to operate over a very broad $V_{\rm CC}$ operating range. The device is specified to operate over the 1.65V to 5.5V $V_{\rm CC}$ range. The inputs tolerate voltages up to 7V independent of $V_{\rm CC}$ operating voltage.

Ordering Information

Part Number	Top Mark	Eco Status	Package	Packing Method
NC7WZ04P6X	Z04	RoHS	6-Lead SC70, EIAJ SC88 1.25mm Wide	3000 Units on Tape & Reel
NC7WZ04L6X	A7	RoHS	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
NC7WZ04FHX	A7	Green	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

Connection Diagrams

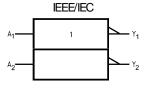


Figure 1. Logic Symbol

Pin Configurations

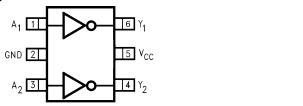


Figure 2. SC70 (Top View)

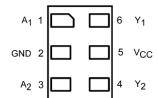


Figure 3. MicroPak (Top Through View)

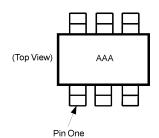


Figure 4. Pin 1 Orientation

Notes:

- 1. AAA represents product code top mark (see Ordering Information).
- 2. Orientation of top mark determines pin one location.
- 3. Reading the top mark left to right, pin one is the low er left pin.

Pin Definitions

Pin # SC70	Pin # MicroPak	Name	Description
1	1	А	Input
2	2	GND	Ground
3	3	А	Input
4	4	Υ	Output
5	5	V _{cc}	Supply Voltage
6	6	Υ	Output

Function Table

Y = /A

Inputs	Output
Α	Υ
L	Н
Н	L

H = HIGH Logic Level

L = LOW Logic Level

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	Min.	Max.	Unit	
V _{cc}	Supply Voltage		-0.5	7.0	V
V _{IN}	DC Input Voltage		-0.5	7.0	V
V _{OUT}	DC Output Voltage		-0.5	7.0	V
l _{IK}	DC Input Diode Current	V _{IN} < -0V		-50	mA
l _{ok}	DC Output Diode Current	V _{OUT} < 0V		-50	mA
l _{OUT}	DC Output Source / Sink Current	DC Output Source / Sink Current			mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current		±100	mA	
T _{STG}	Storage Temperature Range	Storage Temperature Range			°C
TJ	Junction Temperature Under Bia	s		+150	°C
T _L	Junction Lead Temperature (Sol	dering, 10 Seconds)		+260	°C
		SC70-6		180	
P_D	Pow er Dissipation at +85°C	MicroPak-6		130	mW
		MicroPak2-6		120	
ESD	Human Body Model, JEDEC:JESE		4000	V	
EOD	Charge Device Model, JEDEC:JE	SD22-C101		2000	V

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. ON Semiconductor does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit	
V	Supply Voltage Operating		1.65	5.50		
V _{cc}	Supply Voltage Data Retention		1.5	5.5]	
V _{IN}	Input Voltage		0	5.5	V	
V _{OUT}	Output Voltage		0	V _{cc}	V	
		V _{CC} at 1.8V, 2.5V ±0.2V	0	20		
t _r , t _f	Input Rise and Fall Times	V _{CC} at 3.3V ± 0.3V	0	10	ns/V	
		V _{CC} at 5.0V ± 0.5V	0	5		
T _A	Operating Temperature		-40	+85	°C	
		SC70-6		350		
θ_{JA}	Thermal Resistance	MicroPak-6		500	°C/W	
		MicroPak2-6		560		

Note:

4. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

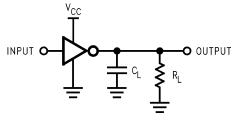
Comple ed	Donom of an	V _{cc} Conditions	Т	T _A =+25°C			T _A =-40 to +85°C			
Symbol	Parameter	V _{cc}	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	
.,	HIGH Level	1.65 to 1.95		0.75V _{CC}			0.75V _{cc}			
Input Voltage		2.30 to 5.50		0.70V _{CC}			0.70V _{CC}		V	
	V _{IL} LOW Level Input	1.65 to 1.95				0.25V _{CC}		0.25V _{CC}	.,	
V _{IL}	Voltage	2.30 to 5.50				0.30V _{CC}		0.30V _{cc}	V	
	1.65		1.55	1.65		1.55				
		1.80		1.70	1.80		1.70			
V _{OH} HIGH Level Output Voltage	2.30	V _{IN} =V _{IL} , I _{OH} =-100μA	2.20	2.30		2.20				
	3.00		2.90	3.00		2.90				
	HIGH Level	4.50		4.40	4.50		4.40		\/	
	Output Voltage	1.65	I _{OH} =-4mA	1.29	1.52		1.29		V	
	2.30	I _{OH} =-8mA	1.90	2.14		1.90				
	3.00	I _{OH} =-16mA	2.40	2.75		2.40				
		3.00	I _{OH} =-24mA	2.30	2.62		2.30			
		4.50	I _{OH} =-32mA	3.80	4.13		3.80			
		1.65			0.10	0.10		0.10		
		1.80			0.00	0.10		0.10		
		2.30	$V_{IN}=V_{IH},\ I_{OL}=100\mu A$		0.00	0.10		0.10		
		3.00			0.00	0.10		0.10		
V	LOW Level	4.50			0.00	0.10		0.10	V	
V_{OL}	Output Voltage	1.65	I _{OL} =4mA		0.80	0.24		0.24	V	
		2.30	I _{OL} =8mA		0.10	0.30		0.30		
		3.00	I _{OL} =16mA		0.16	0.40		0.40		
		3.00	I _{OL} =24mA		0.24	0.55		0.55		
		4.50	I _{OL} =32mA		0.25	0.55		0.55		
I _{IN}	Input Leakage Current	0 to 5.5	$0 \leq V_{IN} \leq 5.5 V$			±1		±1.0	μΑ	
I _{OFF}	Power Off Leakage Current	0	V _{IN} or V _{OUT} =5.5V			1		10	μΑ	
Icc	Quiescent Supply Current	1.65 to 5.50	V _{IN} =5.5V, GND			1		10	μΑ	

AC Electrical Characteristics

Symbol Parameter	Paramotor	V	Conditions		T _A =+25°C		T _A =-40 to +85°C		Units	Figure	
	V _{cc}	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	Figure		
		1.65		1.8	5.3	9.2	1.8	11.0			
	t _{РLH} , t _{РНL} Propagation Delay	1.80		1.8	4.4	7.6	1.8	8.4		Figure 5 Figure 6	
		2.50 ± 0.20	C_{L} =15pF, R_{L} =1M Ω C_{L} =50pF,	1.2	3.0	5.1	1.2	5.6	ns		
t _{PLH} , t _{PHL}		3.30 ± 0.30		0.8	2.2	3.4	0.8	3.8			
		5.00 ± 0.50			0.5	1.8	2.8	0.5	3.1		
		3.30 ± 0.30		1.2	2.9	4.5	1.2	5.0			
	5.00 ± 0.50		5.00 ± 0.50	R _L =500Ω	0.8	2.3	3.6	0.8	4.0		
C _{IN}	Input Capacitance	0.00			2.5				pF		
Power Dissipation	3.30			9				, F	Figure 7		
C_{PD}	Capacitance ⁽⁵⁾	5.00			11				pF	Figure 7	

Note:

5. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: $I_{CCD}=(C_{PD})(V_{CC})(f_{IN})+(I_{CC}\text{static})$.



Notes:

- 6. C_L includes load and stray capacitance.
- 7. Input PRR = 1.0MHz, $t_W = 500ns$.

Figure 5. AC Test Circuit

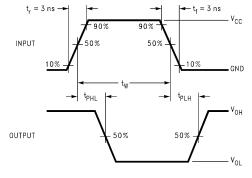
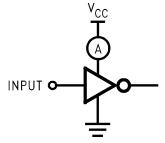


Figure 6. AC Waveforms



Note:

- 8. Input=AC Waveform; t_r=t_f=1.8ns.
- 9. PRR=Variable; Duty Cycle=50%.

Figure 7. I_{CCD} Test Circuit

Physical Dimensions

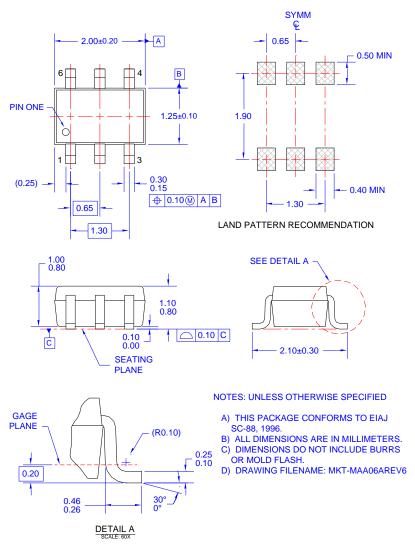


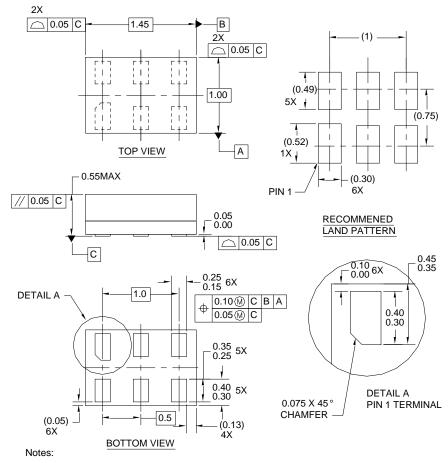
Figure 8. 6-Lead, SC70, EIAJ SC88, 1.25mm Wide

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Tape and Reel Specification

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
P6X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06AREVC

Figure 9. 6-Lead, MicroPak™, 1.0mm Wide

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Tape and Reel Specification

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End) 125 (Typical)		Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions

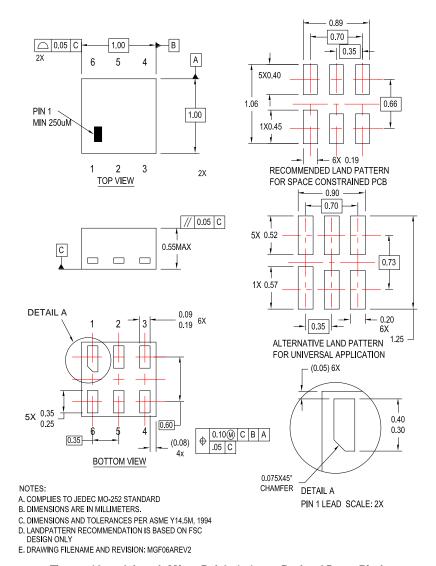


Figure 10. 6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch

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Tape and Reel Specification

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	Leader (Start End)	125 (Typical)	Empty	Sealed
FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

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